

# IRF740B/IRFS740B

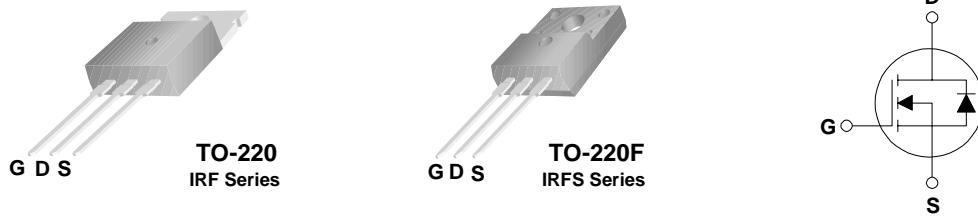
## 400V N-Channel MOSFET

### General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and electronic lamp ballasts based on half bridge.

### Features

- 10A, 400V,  $R_{DS(on)} = 0.54\Omega$  @  $V_{GS} = 10$  V
- Low gate charge ( typical 41 nC)
- Low  $C_{RSS}$  ( typical 35 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	IRF740B	IRFS740B	Units
$V_{DSS}$	Drain-Source Voltage	400		V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	10	10 *	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	6.3	6.3 *	A
$I_{DM}$	Drain Current - Pulsed	(Note 1)	40	A
$V_{GSS}$	Gate-Source Voltage		$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	450	mJ
$I_{AR}$	Avalanche Current	(Note 1)	10	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	13.4	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	5.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	134	44	W
	- Derate above $25^\circ\text{C}$	1.08	0.35	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature

### Thermal Characteristics

Symbol	Parameter	IRF740B	IRFS740B	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.93	2.86	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ\text{C}/\text{W}$

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	400	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.4	--	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 400 \text{ V}$ , $V_{GS} = 0 \text{ V}$	--	--	10	$\mu\text{A}$
		$V_{DS} = 320 \text{ V}$ , $T_C = 125^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	-100	nA

## On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2.0	--	4.0	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 5.0 \text{ A}$	--	0.43	0.54	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 40 \text{ V}$ , $I_D = 5.0 \text{ A}$ (Note 4)	--	9.6	--	S

## Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	--	1400	1800	pF
$C_{oss}$	Output Capacitance		--	150	195	pF
$C_{rss}$	Reverse Transfer Capacitance		--	35	45	pF

## Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 200 \text{ V}$ , $I_D = 10 \text{ A}$ , $R_G = 25 \Omega$	--	20	50	ns
$t_r$	Turn-On Rise Time		--	80	170	ns
$t_{d(off)}$	Turn-Off Delay Time		--	125	260	ns
$t_f$	Turn-Off Fall Time		--	85	180	ns
$Q_g$	Total Gate Charge	$V_{DS} = 320 \text{ V}$ , $I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$	--	41	53	nC
$Q_{gs}$	Gate-Source Charge		--	7	--	nC
$Q_{gd}$	Gate-Drain Charge		--	17	--	nC
			(Note 4, 5)			

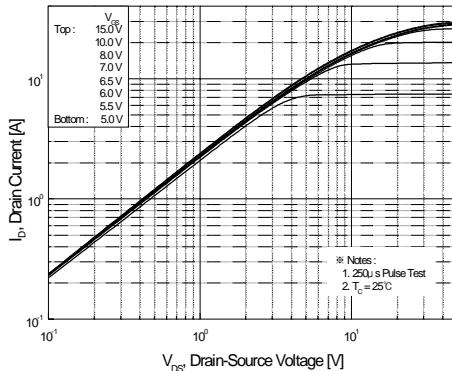
## Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	10	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	40	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$ , $I_S = 10 \text{ A}$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0 \text{ V}$ , $I_S = 10 \text{ A}$ , $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	330	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	3.57	--	$\mu\text{C}$

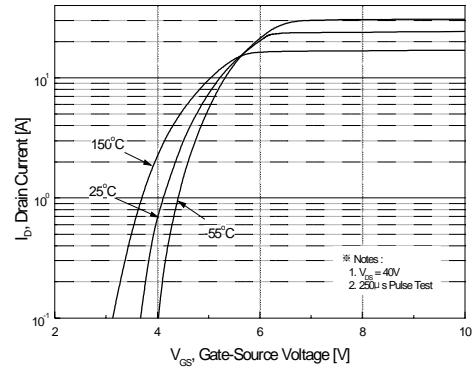
### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 7.9\text{mH}$ ,  $I_{AS} = 10\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25 \Omega$ . Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 10\text{A}$ ,  $dI/dt \leq 300\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

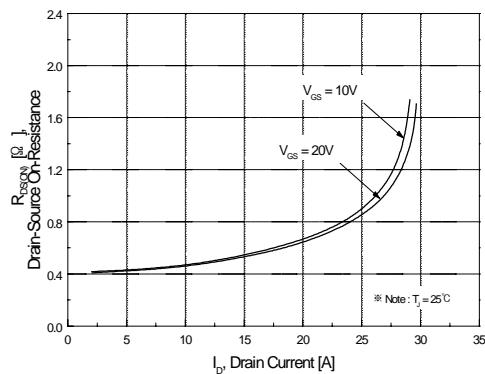
## Typical Characteristics



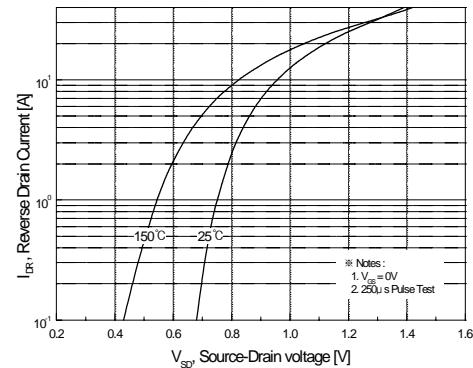
**Figure 1. On-Region Characteristics**



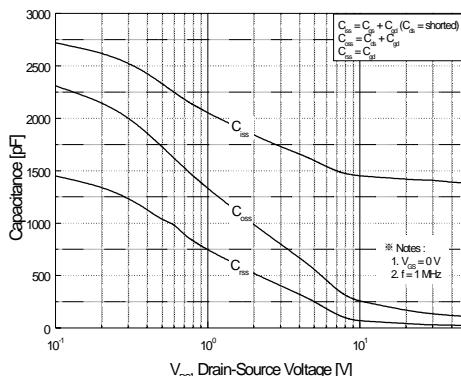
**Figure 2. Transfer Characteristics**



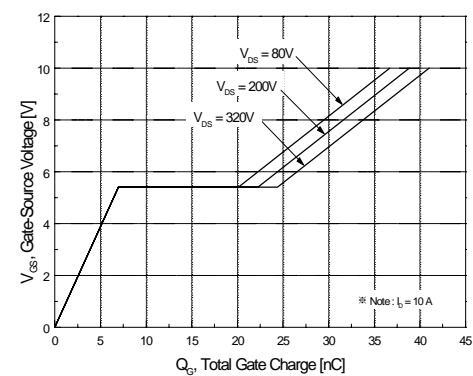
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**